



CHENMKO ENTERPRISE CO.,LTD

SURFACE MOUNT

Dual Enhancement Mode Field Effect Transistor

N-channel: VOLTAGE 30 Volts CURRENT 0.2 Ampere
P-channel: VOLTAGE 30 Volts CURRENT 0.2 Ampere



Halogens free devices

APPLICATION

- * High speed switching , Analog switching

FEATURE

- * Small flat package. (ÜÓÍÍ SOT-H63)
- * Super high dense cell design for extremely low R_{DS(ON)}.
- * Lead free product is acquired.
- * High power and current handing capability.
- * ESD protect in input gate 2KV

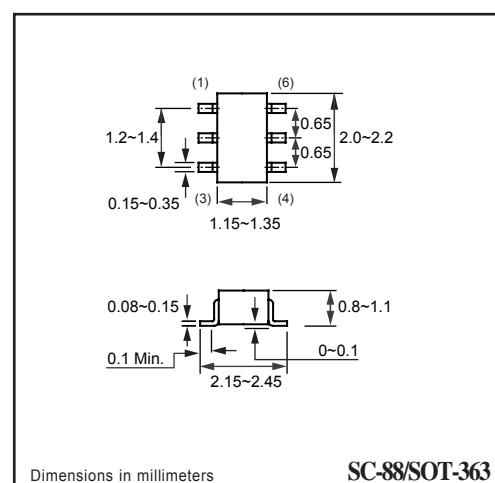
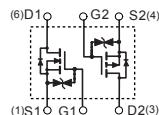
CONSTRUCTION

- * N-Channel & P-Channel Enhancement in the package



SC-88/SOT-363

CIRCUIT



Dimensions in millimeters

SC-88/SOT-363

Absolute Maximum Ratings

T_A = 25°C unless otherwise noted

Symbol	Parameter	N-Channel	P-Channel	Units
V _{DSS}	Drain-Source Voltage	30	-30	V
V _{GSS}	Gate-Source Voltage	±8	±8	V
I _D	Maximum Drain Current - Continuous	200	-200	mA
	- Pulsed (Note 3)	400	-400	
P _D	Maximum Power Dissipation	150		mW
T _J	Operating Temperature Range	-55 to 125		°C
T _{STG}	Storage Temperature Range	-55 to 125		°C

Note : 1. Surface Mounted on FR4 Board , t <=10sec

2. Pulse Test , Pulse width <= 300us , Duty Cycle <= 2%

3. Repetitive Rating , Pulse width limited by maximum junction temperature

4. Guaranteed by design , not subject to production testing

201GÉ

ELECTRICAL CHARACTERISTIC (CHM3U22GESGP)

N-Channel Electrical Characteristics $T_A = 25^\circ\text{C}$ unless otherwise noted

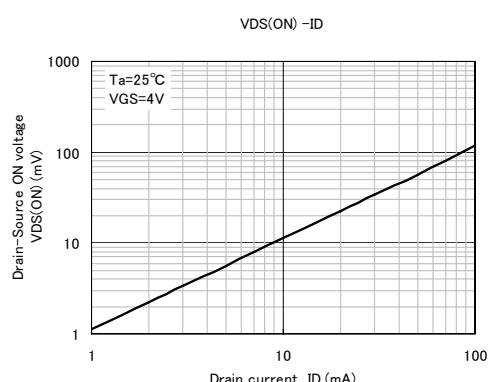
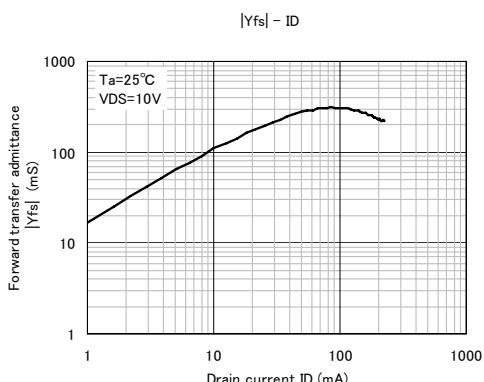
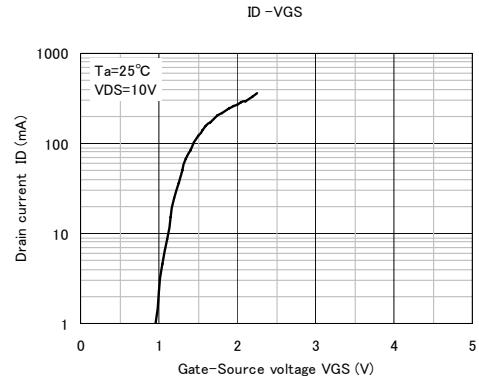
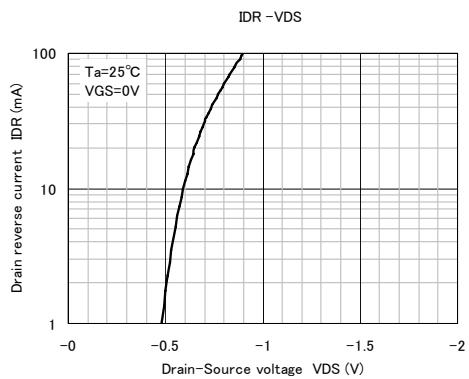
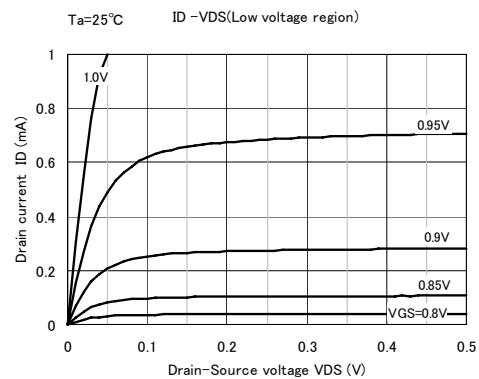
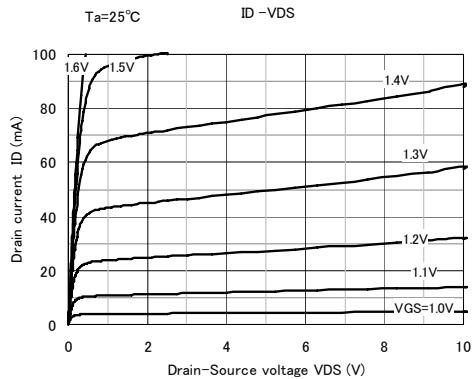
SYMBOL	Parameter	Test conditions				Unit
			Min	Typ	Max	
$V(BR)DSS$	Drain-source breakdown voltage	$I_D=100\mu\text{A}, V_{GS}=0\text{V}$	30	—	—	V
I_{GSS}	Gate-source leak current	$V_{GS}=\pm 5\text{V}, V_{DS}=0\text{V}$	—	—	± 0.5	μA
I_{DSS}	Zero gate voltage drain current	$V_{DS}=30\text{V}, V_{GS}=0\text{V}$	—	—	1.0	μA
V_{th}	Gate threshold voltage	$I_D=250\mu\text{A}, V_{DS}=V_{GS}$	0.6	—	1.2	V
$ Y_{fs} $	Forward transfer admittance	$V_{DS}=10\text{V}, I_D=0.1\text{A}$	—	300	—	mS
$R_{DS(ON)}$	Static drain-source on-state resistance	$I_D=100\text{mA}, V_{GS}=4.0\text{V}$	—	1.1	—	Ω
C_{iss}	Input capacitance	$V_{DS}=10\text{V}, V_{GS}=0\text{V}, f=1\text{MHz}$	—	33	—	pF
C_{oss}	Output capacitance		—	6.8	—	
t_{on}	Switching time	$V_{DD}=5\text{V}, I_D=10\text{mA}$	—	12	—	ns
t_{off}		$V_{GS}=0\sim 5\text{V}$	—	80	—	

P-Channel Electrical Characteristics $T_A = 25^\circ\text{C}$ unless otherwise noted

SYMBOL	Parameter	Test conditions				Unit
			Min	Typ	Max	
$V(BR)DSS$	Drain-source breakdown voltage	$I_D=-100\mu\text{A}, V_{GS}=0\text{V}$	-30	—	—	V
I_{GSS}	Gate-source leak current	$V_{GS}=\pm 5\text{V}, V_{DS}=0\text{V}$	—	—	± 0.5	μA
I_{DSS}	Zero gate voltage drain current	$V_{DS}=-30\text{V}, V_{GS}=0\text{V}$	—	—	-1.0	μA
V_{th}	Gate threshold voltage	$I_D=-250\mu\text{A}, V_{DS}=V_{GS}$	-0.6	—	-1.2	V
$ Y_{fs} $	Forward transfer admittance	$V_{DS}=-10\text{V}, I_D=-0.1\text{A}$	—	220	—	mS
$R_{DS(ON)}$	Static drain-source on-state resistance	$I_D=-100\text{mA}, V_{GS}=-4.0\text{V}$	—	3.0	—	Ω
C_{iss}	Input capacitance	$V_{DS}=-10\text{V}, V_{GS}=0\text{V}, f=1\text{MHz}$	—	35	—	pF
C_{oss}	Output capacitance		—	7.3	—	
t_{on}	Switching time	$V_{DD}=-5\text{V}, I_D=-10\text{mA}$	—	14	—	ns
t_{off}		$V_{GS}=0\sim -5\text{V}$	—	100	—	

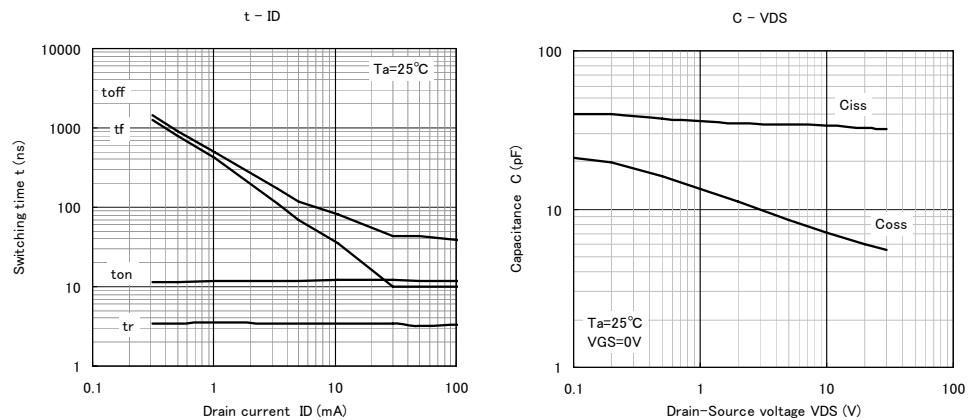
RATING CHARACTERISTIC CURVES (CHM3U22GESGP)

N-MOSFET Typical Electrical Characteristics

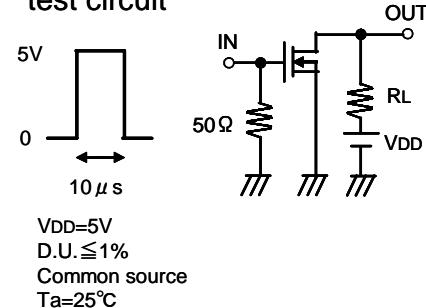


RATING CHARACTERISTIC CURVES (CHM3U22GESGP)

N-MOSFET Typical Electrical Characteristics

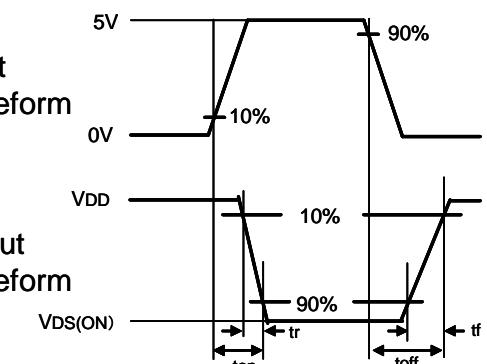


test circuit



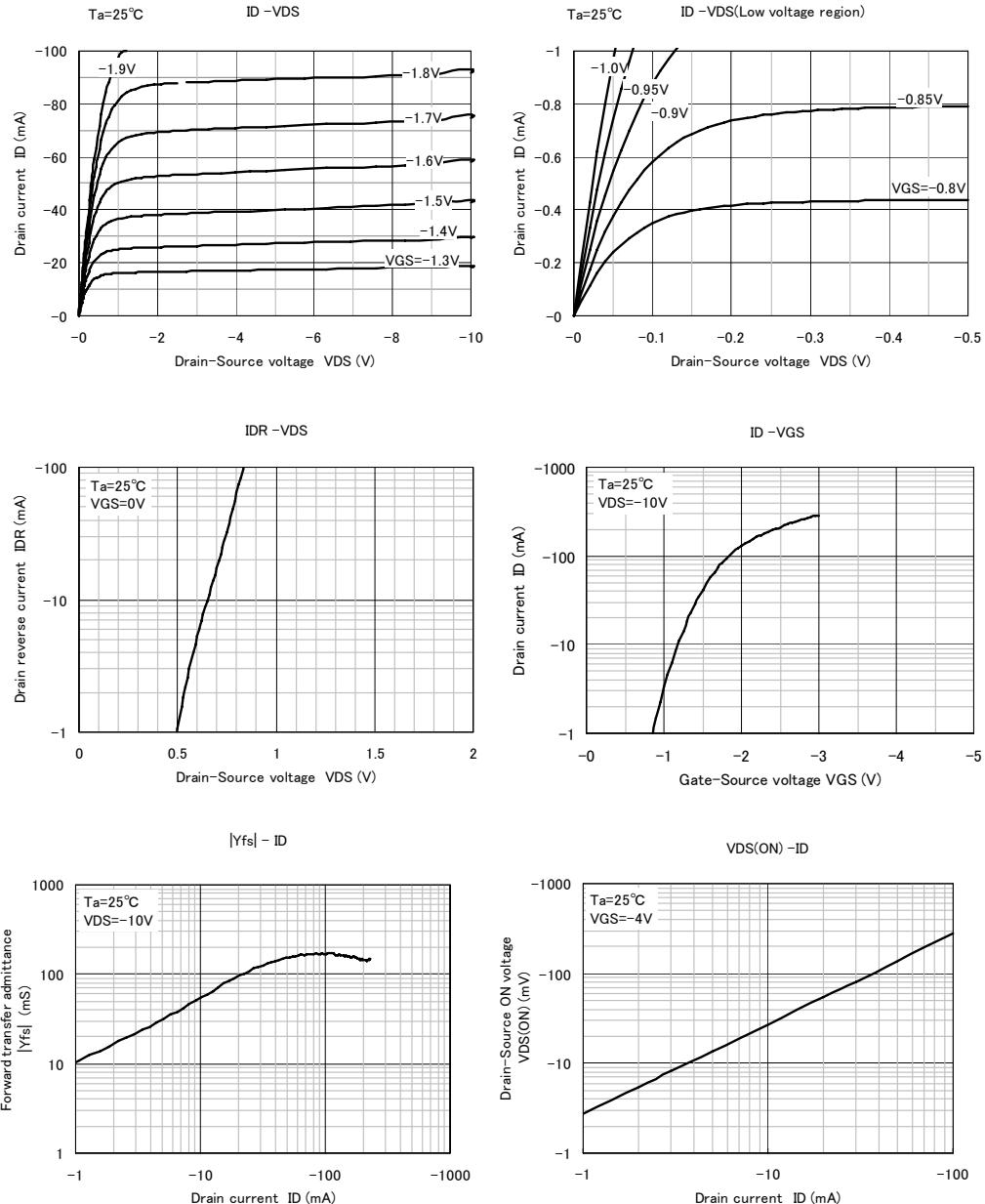
input waveform

output waveform



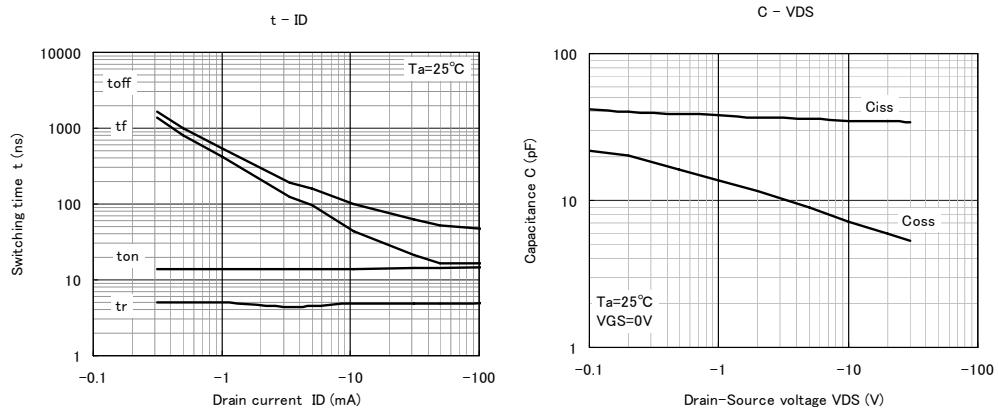
RATING CHARACTERISTIC CURVES (CHM3U22GESGP)

P-MOSFET Typical Electrical Characteristics



RATING CHARACTERISTIC CURVES (CHM3U22GESGP)

P-MOSFET Typical Electrical Characteristics



test circuit

